

# Solder wire DHB-RMA3-NP303

## Product description

GENMA solder wire – our DHB-RMA3-NP303 solder wire convinces with its extremely quick wetting properties during automated iron-soldering processes. This solder wire is especially suitable for soldering processes that are used, for example, to fix enclosures to boards in continuous soldering operations. Cleaning after soldering is not necessary.

## Technical properties

|                                                | Specific value                                    |     |           |                       | Testing method      |
|------------------------------------------------|---------------------------------------------------|-----|-----------|-----------------------|---------------------|
| <b>Diameter (mm)</b>                           | 0,15                                              | 0,3 | 0,5 / 0,6 | 0,8 / 1,0 / 1,2 / 1,6 |                     |
| <b>Weight spindle (g)</b>                      | 50                                                | 250 | 500       | 1000                  |                     |
| <b>Flux type</b>                               | ROL1, no clean                                    |     |           |                       | IPC J-STD-004B      |
| <b>Flux content (wt%)</b>                      | 3,18 ± 0,30 %                                     |     |           |                       | IPC-TM-650 2.3.34.1 |
| <b>Halide content (wt%)</b>                    | 0,07 ± 0,03 %                                     |     |           |                       | IPC-TM-650 2.3.35   |
| <b>Insulation resistance (Ω)</b>               | > 1 x 10 <sup>10</sup> ( 40°C 90% rel. humidity ) |     |           |                       | IPC-TM-650 2.6.3.3  |
| <b>Insulation resistance (Ω)</b>               | > 1 x 10 <sup>8</sup> ( 85°C 85% rel. humidity )  |     |           |                       | IPC-TM-650 2.6.3.3  |
| <b>Migration</b>                               | non                                               |     |           |                       | IPC-TM-650 2.6.14   |
| <b>Recommended solder tip temperature (°C)</b> | 350 ± 20                                          |     |           |                       |                     |
| <b>Recommended storage (°C)</b>                | 0 - 40                                            |     |           |                       |                     |

## Alloys

| Name         | Alloy                              | Melting temperature range | Advantages                        |
|--------------|------------------------------------|---------------------------|-----------------------------------|
| <b>NP303</b> | Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305 | 217 - 221                 | Standard alloy, excellent wetting |

## Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and Polyfluoroalkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.